DATA SHEET

74LVC245A/74LVCH245A

Octal bus transceiver with direction pin with 5-volt tolerant inputs/outputs (3-State)

Product specification
Supersedes data of 1997 Dec 19
IC24 Data Handbook

1998 May 20

Philips
Semiconductors

PHILIPS

Octal bus transceiver with direction pin with 5-volt tolerant inputs/outputs (3-State)

74LVC245A 74LVCH245A

FEATURES

- 5-volt tolerant inputs/outputs, for interfacing with 5-volt logic
- Supply voltage range of 2.7V to 3.6V
- Complies with JEDEC standard no. 8-1A
- CMOS low power consumption
- Direct interface with TTL levels
- High impedance when V_{CC} = 0V
- Bushold on all data inputs (74LVCH245A only)

DESCRIPTION

The 74LVC245A/74LVCH245A is a high-performance, low-power, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3V or 5V devices. In 3-State operation, outputs can handle 5V. These features allow the use of these devices as translators in a mixed 3.3V/5V environment.

The 74LVC245A/74LVCH245A is an octal transceiver featuring non-inverting 3-State bus compatible outputs in both send and receive directions. The '245' features an output enable ($\overline{OE}$) input for easy cascading and a send/receive (DIR) input for direction control. $\overline{OE}$ controls the outputs so that the buses are effectively isolated.

The '245' is functionally identical to the '640', but the '640' has true (non-inverting) outputs.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t_{PHL}/t_{PLH}	Propagation delay A_n to B_n; B_n to A_n	C_L = 50pF V_{CC} = 3.3V	3.6	ns
C_I	Input capacitance		5.0	pF
$C_{I/O}$	Input/output capacitance		10.0	pF
C_{PD}	Power dissipation capacitance per buffer	Notes 1 and 2	33	pF

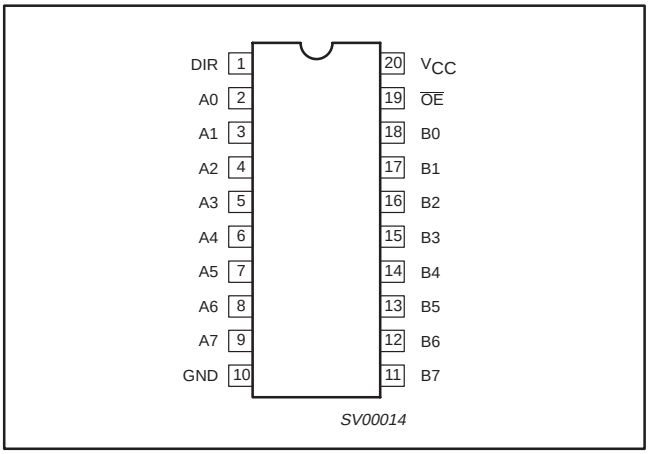
NOTE:

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW):
   $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where:
   f_i = input frequency in MHz; C_L = output load capacity in pF;
   f_o = output frequency in MHz; V_{CC} = supply voltage in V;
   $\Sigma (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.
2. The condition is V_I = GND to V_{CC}

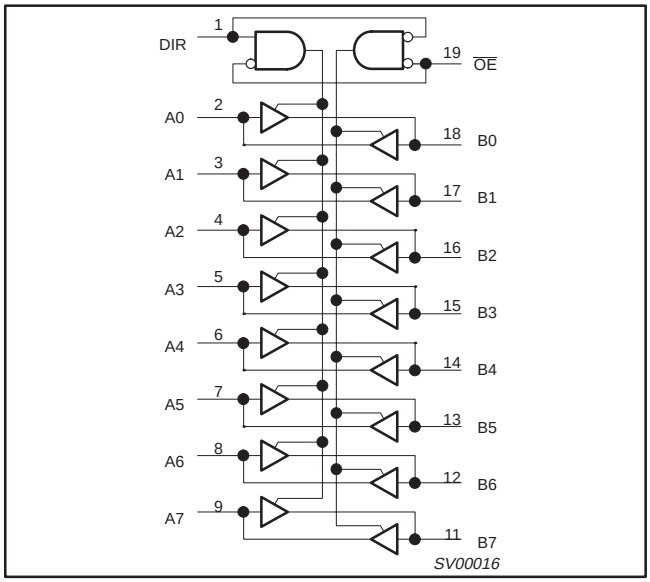
ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
20-Pin Plastic Shrink Small Outline (SO)	–40°C to +85°C	74LVC245A D	74LVC245A D	SOT163-1
20-Pin Plastic Shrink Small Outline (SSOP) Type II	–40°C to +85°C	74LVC245A DB	74LVC245A DB	SOT339-1
20-Pin Plastic Thin Shrink Small Outline (TSSOP) Type I	–40°C to +85°C	74LVC245A PW	7LVC245APW DH	SOT360-1
20-Pin Plastic Shrink Small Outline (SO)	–40°C to +85°C	74LVCH245A D	74LVCH245A D	SOT163-1
20-Pin Plastic Shrink Small Outline (SSOP) Type II	–40°C to +85°C	74LVCH245A DB	74LVCH245A DB	SOT339-1
20-Pin Plastic Thin Shrink Small Outline (TSSOP) Type I	–40°C to +85°C	74LVCH245A PW	LVCH245APW DH	SOT360-1

PIN CONFIGURATION



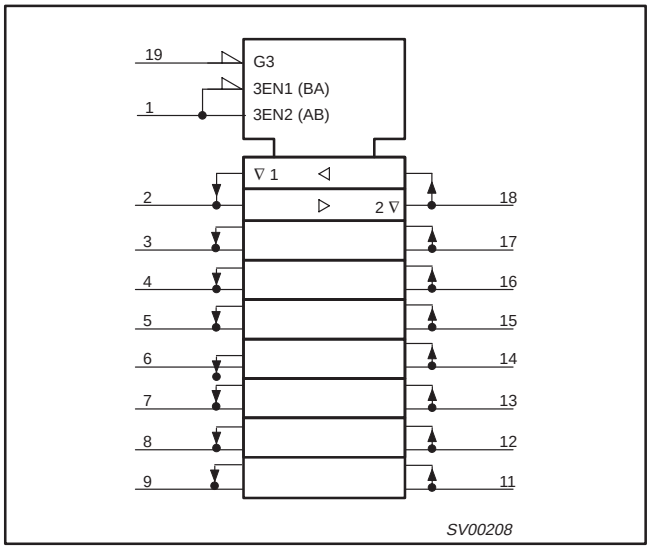
LOGIC SYMBOL



PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1	DIR	Direction control
2, 3, 4, 5, 6, 7, 8, 9	A_0 to A_7	Data inputs/outputs
10	GND	Ground (0V)
18, 17, 16, 15, 14, 13, 12, 11	B_0 to B_7	Data inputs/outputs
19	$\overline{OE}$	Output enable input (active-Low)
20	V_{CC}	Positive supply voltage

LOGIC SYMBOL (IEEE/IEC)



FUNCTION TABLE

INPUTS		INPUTS/OUTPUTS	
$\overline{OE}$	DIR	An	B_0
L	L	A = B	Inputs
L	H	Inputs	B = A
H	X	Z	Z

H = HIGH voltage level
L = LOW voltage level
X = Don't care
Z = High impedance OFF-state

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIMITS		UNIT
			MIN	MAX	
V_{CC}	DC supply voltage (for max. speed performance)		2.7	3.6	V
	DC supply voltage (for low-voltage applications)		1.2	3.6	
V_I	DC Input voltage range		0	5.5	V
V_O	DC Output voltage range; output HIGH or LOW state		0	V_{CC}	V
	DC output voltage range; output 3-State		0	5.5	
T_{amb}	Operating ambient temperature range in free-air		–40	+85	°C
t_r, t_f	Input rise and fall times	V_{CC} = 1.2 to 2.7V V_{CC} = 2.7 to 3.6V	0 0	20 10	ns/V

ABSOLUTE MAXIMUM RATINGS[1]

In accordance with the Absolute Maximum Rating System (IEC 134)
Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		–0.5 to +6.5	V
I_{IK}	DC input diode current	$V_I < 0$	–50	mA
V_I	DC input voltage	Note 2	–0.5 to +6.5	V
I_{OK}	DC output diode current	$V_O > V_{CC}$ or $V_O < 0$	±50	mA
V_O	DC output voltage; output HIGH or LOW state	Note 2	–0.5 to V_{CC} +0.5	V
	DC output voltage; output 3-State	Note 2	–0.5 to 6.5	
I_O	DC output source or sink current	V_O = 0 to V_{CC}	±50	mA
I_{GND}, I_{CC}	DC V_{CC} or GND current		±100	mA
T_{stg}	Storage temperature range		–65 to +150	°C
P_{TOT}	Power dissipation per package – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	 above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	 500 500	mW

NOTES:
1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			Temp = -40°C to +85°C			
			MIN	TYP[1]	MAX	
V_{IH}	HIGH level Input voltage	V_{CC} = 1.2V	V_{CC}			V
		V_{CC} = 2.7 to 3.6V	2.0			
V_{IL}	LOW level Input voltage	V_{CC} = 1.2V			GND	V
		V_{CC} = 2.7 to 3.6V			0.8	
V_{OH}	HIGH level output voltage	V_{CC} = 2.7V; $V_I = V_{IH}$ or V_{IL}; I_O = –12mA	V_{CC} – 0.5			V
		V_{CC} = 3.0V; $V_I = V_{IH}$ or V_{IL}; I_O = –100µA	V_{CC} – 0.2	V_{CC}		
		V_{CC} = 3.0V; $V_I = V_{IH}$ or $V_{IL;}$ I_O = –18mA	V_{CC} – 0.6			
		V_{CC} = 3.0V; $V_I = V_{IH}$ or $V_{IL;}$ I_O = –24mA	V_{CC} – 0.8			
V_{OL}	LOW level output voltage	V_{CC} = 2.7V; $V_I = V_{IH}$ or V_{IL}; I_O = 12mA			0.40	V
		V_{CC} = 3.0V; $V_I = V_{IH}$ or V_{IL}; I_O = 100µA			0.20	
		V_{CC} = 3.0V; $V_I = V_{IH}$ or $V_{IL;}$ I_O = 24mA			0.55	
I_I	Input leakage current[6]	V_{CC} = 3.6V; V_I = 5.5V or GND		±0.1	±5	µA
I_{OZ}	3-State output OFF-state current[6, 7]	V_{CC} = 3.6V; $V_I = V_{IH}$ or V_{IL}; V_O = 5.5V or GND		0.1	±5	µA
I_{off}	Power off leakage supply	V_{CC} = 0.0V; V_I or V_O = 5.5V		0.1	±10	µA
I_{CC}	Quiescent supply current	V_{CC} = 3.6V; $V_I = V_{CC}$ or GND; I_O = 0		0.1	10	µA
ΔI_{CC}	Additional quiescent supply current per input pin	V_{CC} = 2.7V to 3.6V; $V_I = V_{CC}$ –0.6V; I_O = 0		5	500	µA
I_{BHL}	Bushold LOW sustaining current[2, 3, 4]	V_{CC} = 3.0V; V_I =0.8V	75	–	–	µA
I_{BHH}	Bushold HIGH sustaining current[2, 3, 4]	V_{CC} = 3.0V; V_I =2.0V	–75	–	–	µA
I_{BHLO}	Bushold LOW overdrive current[2, 3, 5]	V_{CC} = 3.6V	500	–	–	µA
I_{BHHO}	Bushold HIGH overdrive current[2, 3, 5]	V_{CC} = 3.6V	–500	–	–	µA

NOTES:

1. All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.
2. Valid for data inputs of bushold parts (LVCH-A) only.
3. For data inputs only, control inputs do not have a bushold circuit.
4. The specified sustaining current at the data input holds the input below the specified V_I level.
5. The specified overdrive current at the data input forces the data input to the opposite logic input state.
6. For bushold parts, the bushold circuit is switched off when V_I exceeds V_{CC} allowing 5.5V on the input terminal.
7. For I/O ports the parameter I_{OZ} includes the input leakage current.

AC CHARACTERISTICS

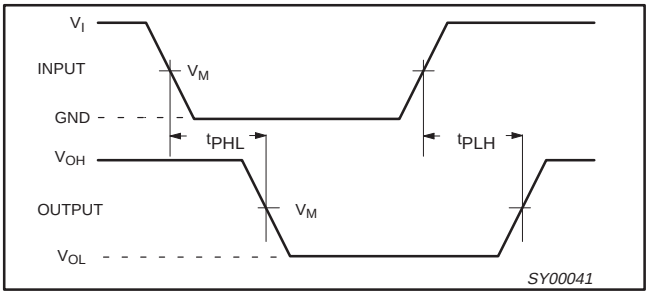
GND = 0V; $t_r = t_f \leq 2.5$ns; $C_L = 50$pF; $R_L = 500\Omega$; $T_{amb} = -40°C$ to $+85°C$.

SYMBOL	PARAMETER	WAVEFORM	LIMITS						UNIT
			V_{CC} = 3.3V ±0.3V			V_{CC} = 2.7V		V_{CC} = 1.2V	
			MIN	TYP[1]	MAX	MIN	MAX	TYP	
t_{PHL} t_{PLH}	Propagation delay A_n to B_n; B_n to A_n	1, 3	1.5	3.6	6.3	1.5	7.3	16	ns
t_{PZH} t_{PZL}	3-State output enable time $\overline{OE}$ to A_n; $\overline{OE}$ to B_n	2, 3	1.5	5.1	8.5	1.5	9.5	23	ns
t_{PHZ} t_{PLZ}	3-State output disable time $\overline{OE}$ to A_n; $\overline{OE}$ to B_n	2, 3	1.5	4.5	7.0	1.5	8.0	16	ns

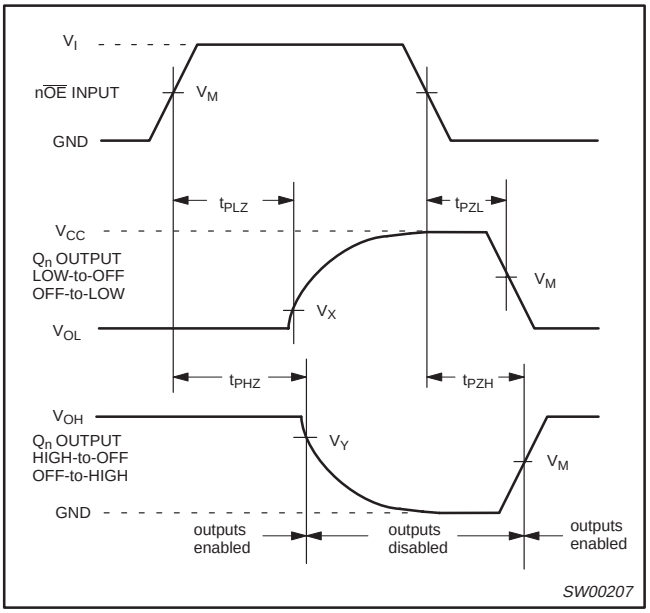
NOTE:
1. Unless otherwise stated, all typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

AC WAVEFORMS

V_M = 1.5V at $V_{CC} \geq 2.7$V; V_M = 0.5 V_{CC} at $V_{CC} < 2.7$V.
V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.
$V_X = V_{OL}$ + 0.3V at $V_{CC} \geq 2.7$V; $V_X = V_{OL}$ + 0.1 V_{CC} at $V_{CC} < 2.7$V
$V_Y = V_{OH}$ –0.3V at $V_{CC} \geq 2.7$V; $V_Y = V_{OH}$ – 0.1 V_{CC} at $V_{CC} < 2.7$V

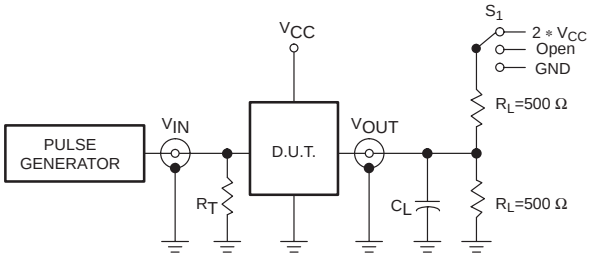


Waveform 1. Input (D_n) to output (Qn) propagation delays.



Waveform 2. 3-State enable and disable times.

TEST CIRCUIT



Test Circuit for 3-State Outputs

SWITCH POSITION

TEST	SWITCH
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 * V_{CC}
t_{PHZ}/t_{PZH}	GND

V_{CC}	V_{IN}
< 2.7V	V_{CC}
2.7 – 3.6V	2.7V

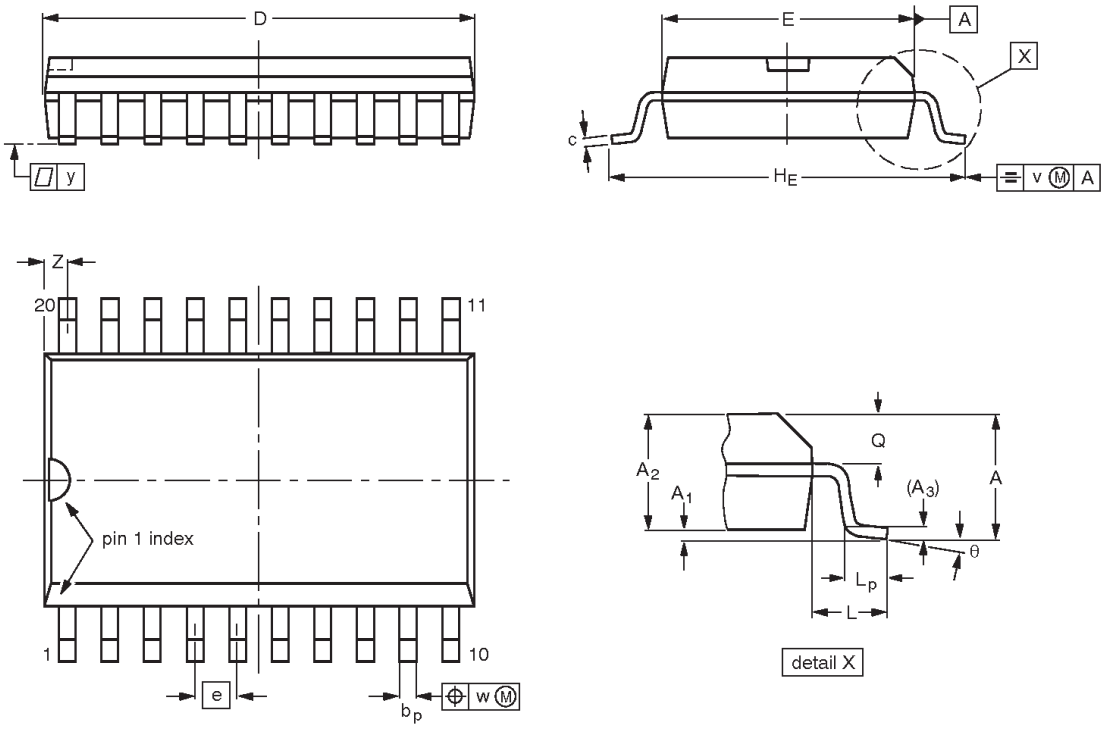
DEFINITIONS

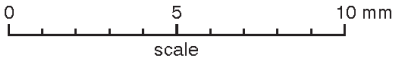
R_L = Load resistor
C_L = Load capacitance includes jig and probe capacitance
R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

SW00047

Waveform 3. Load circuitry for switching times.

SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**





DIMENSIONS (inch dimensions are derived from the original mm dimensions)

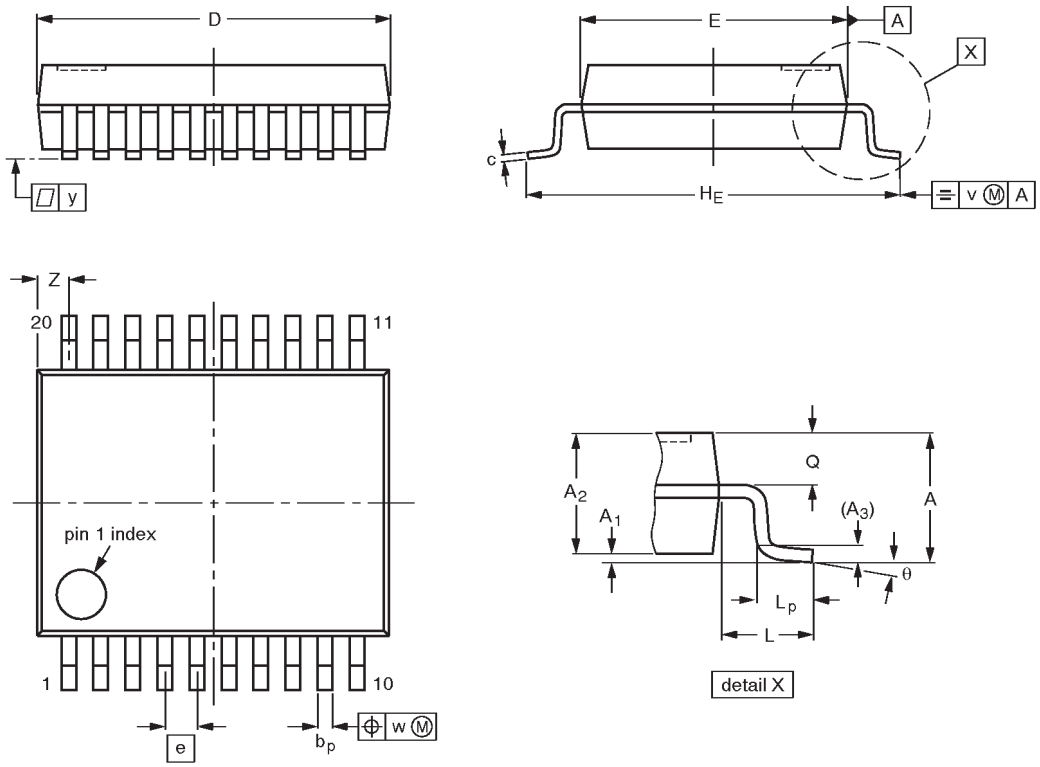
UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8^o 0^o
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

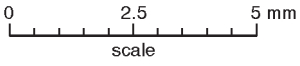
Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				~~92-11-17~~ 95-01-24

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm **SOT339-1**





DIMENSIONS (mm are the original dimensions)

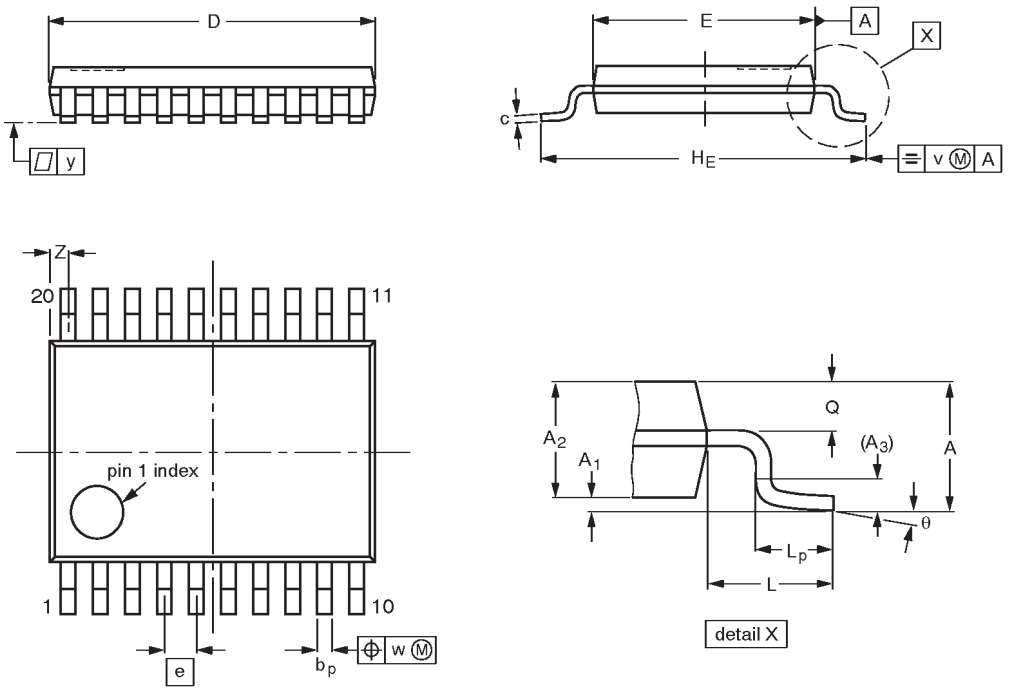
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

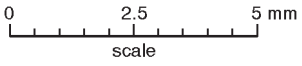
Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT339-1		MO-150AE				~~93-09-08~~ 95-02-04

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm **SOT360-1**





DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT360-1		MO-153AC				~~93-06-16~~ 95-02-04